Product Change Notification

Change Notification #:	**114630 - 00**
Change Title:	**Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS, PCN 114630-00, Product Design, Manufacturing Process Change for QSFP Cage Attach**
Date of Publication:	**May 24, 2016**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	May 20, 2016

Description of Change to the Customer:

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Affected Product Code	Product Description
100HFA016LS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x16 Low Profile 100HFA016LS

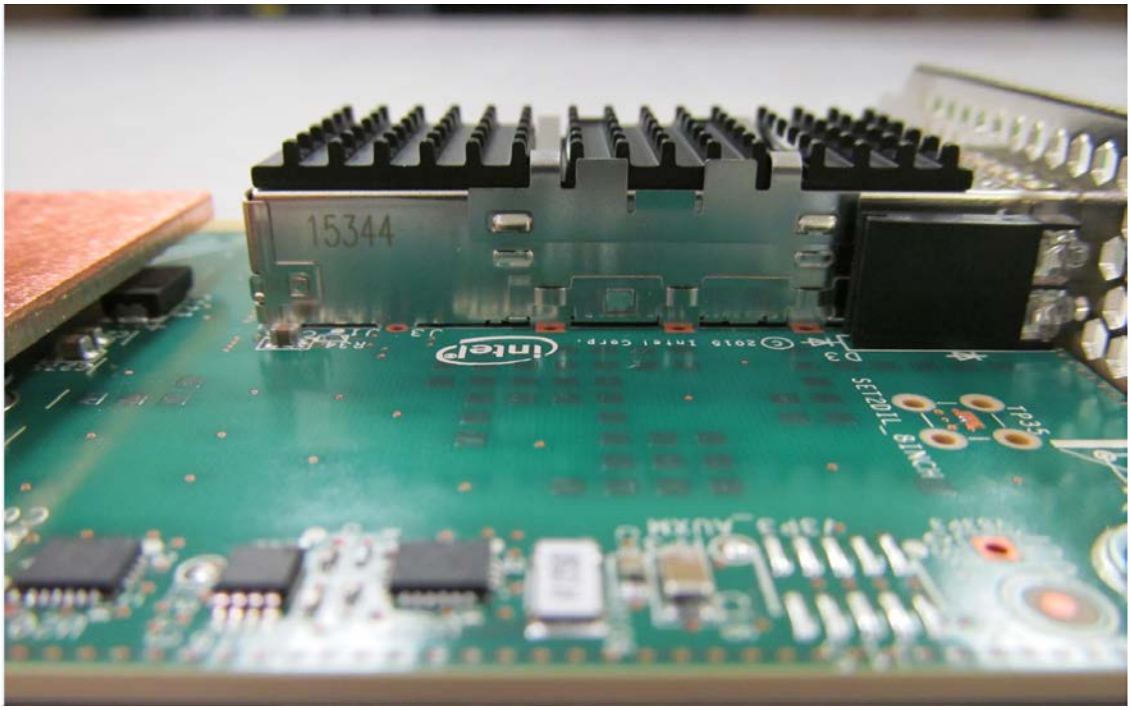
Overview of Changes:

An issue has been identified with Intel® Omni-Path adapters that can result in unseating of the mechanical cage assembly over the Quad Small Form-factor Pluggable (QSFP) connector. Unseating of the QSFP cage assembly may prevent successful insertion of a cable QSFP module into a board connector due to guide misalignment. Electrical connectivity between the cable QSFP module and board QSFP connector is not compromised by a loose QSFP cage and QSFP modules successfully inserted and latched into board QSFP connectors will maintain expected electrical and thermal performance.

Product Material Change Details:

Intel has added a step to the manufacturing process for all Omni-Path adapters to solder QSFP cage assembly press-fit pins to the adapter laminate to eliminate the possibility of unseating of QSFP cage assemblies. This change does not impact form, fit or function of the adapter. The manufacturing process change implemented has been evaluated to ensure no quality, reliability or functional impacts to our customers.


Unseated QSFP cage assembly


Properly Seated QSFP cage assembly

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.

Any adapters identified through visual inspection to have a loose or unseated QSFP cage assembly should be RMA'd to Intel for replacement or credit according to their warranty coverage. Customers with unopened adapters shipped from Intel before May 16, 2016 may also return their adapters to Intel for replacement or credit according to their warranty coverage. Adapters functioning properly in running systems require no action.

There is no change to adapter Intel Material Master (MM) numbers. The manufacturing process change outlined in this PCN is traceable through serial number date code.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#
100HFA016LS	948159

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
May 24, 2016	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

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